### 501874454 04/02/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Byung Tai Do	03/22/2012
Arnel Senosa Trasporto	03/22/2012
Linda Pei Ee Chua	03/22/2012

# RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.	
Street Address:	ess: 10 Ang Mo Kio Street 65	
Internal Address:	#05-17/20 Techpoint	
City:	Singapore	
State/Country:	SINGAPORE	
Postal Code:	569059	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13427598

# CORRESPONDENCE DATA

Fax Number: (408)738-0881 Phone: 408-738-0592

Email: efiling@ishimarulaw.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US

Mail.

Correspondent Name: ISHIMARU & ASSOCIATES LLP

Address Line 1: 2055 Gateway Place

Address Line 2: Suite 700

Address Line 4: San Jose, CALIFORNIA 95110

ATTORNEY DOCKET NUMBER:	27-856
NAME OF SUBMITTER:	Mikio Ishimaru

## Total Attachments: 3

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> PATENT REEL: 027970 FRAME: 0813

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Docket No.: 27-856

#### ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

# INTEGRATED CIRCUIT PACKAGING SYSTEM WITH LEADFRAME LEAD ARRAY ROUTING AND METHOD OF MANUFACTURE THEREOF

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, <u>STATS ChipPAC Ltd.</u>, a Corporation of the <u>Republic of Singapore</u>, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

- 1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
- 2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
- 3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

Lof3

Docket No.: 27-856

4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this Non Provisional application and that of the Provisional application from which it claims priority in the spaces that follow:

Serial Number: 61/549,347 Filing Date: October 20, 2011

Serial Number: 13/427,598 Filing Date: March 22,2012

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Byung Tai Do

Vo Tuong Minh

12 mar 2012

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Arnel Senosa Trasporto

Witness Signature

Tuong Minh Print Witness Name

22 Mar 2012 Date

Witness Signature

2017 )) mar

Date

Docket No.: 27-856 ASSIGNMENT

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Gr.		22 mar 2012	
	Linda Pei Ee Chua	ाका जानानीका गांजानीका का का	Date
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	Witness Signature		Witness Signature
	2 Vo Tuong Minh	1	Lau Wan Thy
-	Print Witness Name		Print Witness Name
į	22 Mar 2012		22 Mar 2012
	Date	***************************************	Date